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#7/1/15734
1-16-03
PATENT
SP01 -325

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Joseph F. Mach

Group Art Unit: 1754

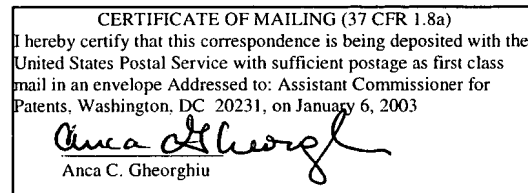
Serial No.: 09/991,401

Examiner: C. A. Fiorilla

Filing Date: November 20, 2001

Title: COMPRESSION-MOLDED SILICON
CARBIDE STRUCTURES

BOX NON-FEE AMENDMENT
Assistant Commissioner for Patents
Washington, DC 20231



Sir:

RESPONSE TO THE EXAMINER'S OFFICE ACTION

In reply to the Office Action dated 10/04/2002, designated as Paper No. 6 in the above-captioned application, please enter the following amendments and remarks as follows:

In the Claims

Please cancel claims 9, 17-36 without prejudice.

Please replace claims 1 and 10 with the following amended claims:

1. (Amended) A process for forming a silicon carbide structure, comprising:
- forming a mixture of a silicon precursor powder, a cross-linking thermoset resin and a silicon-containing filler selected from powder of the group consisting of silicon carbide, silicon nitride and silicate materials;
- compression molding the mixture to form a rigid structure;
- carbonizing the rigid structure in an inert atmosphere at a temperature in a range from about 700 to 1000°C to convert the cross-linking thermoset resin to carbon;
- and
- heating the rigid structure in an inert atmosphere to a temperature in a range from about 1400 to 1800°C to allow the carbon to react with silicon in the rigid structure to form silicon carbide.

10. (Amended) The process of claim 1, wherein the silicon-containing filler is silicon carbide.